



# Advanced Semiconductor Packaging & Chiplet Show 2025

2025. 8. **27(WED)** - **29(FRI)**  
Suwon Convention Center,  
South Korea



Hosted by



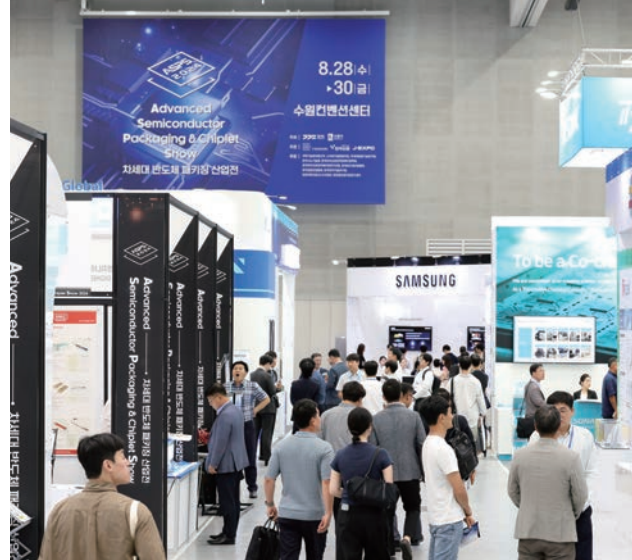
Organized by





## SHOW OVERVIEW

- Show Title** Advanced Semiconductor Packaging & Chiplet Show 2025
- Abbr.** ASPS 2025
- Dates** August 27(WED) – 29(FRI), 2025
- Hours** 10:00 – 17:00 (16:30 on Friday)
- Venue** Suwon Convention Center (SCC), South Korea
- Scale** 150 exhibitors, 500 booths, 10,000 visitors
- Hosted by** Gyeonggi-do, Suwon City
- Organized by** J. EXPO, Suwon Convention Center, Electronic Times
- Supported by** Advanced Institute of Convergence Technology,  
Korea Advanced Nano Fab Center,  
Korea Electronics Technology Institute,  
Korea Packaging Integration Association,  
Korea Semiconductor Industry Association,  
SoBuJang Technology Collaboration Forum,  
The Korean Association of Microelectronics Packaging,  
The Korean Microelectronics and Packaging Society,  
Hanyang Center for Advanced Semiconductor Packaging,  
HYU LINC 3.0



## CONCURRENT EVENTS



Semiconductor Packaging  
Trend Forum (SPTF)



Symposium by SBJ & KAMP



Exhibitor Tech Seminar & Etc.





## EXHIBITS



Semiconductor Packaging Test & Processing Equipment



Semiconductor Packaging Materials & Parts



Semiconductor Packaging Technical Solutions & EDA Software



Semiconductor Packaging Glass Substrate



Other Wafer Processing Materials, Parts, and Equipment



## VISITOR PROFILE

GLOBAL IDM



GLOBAL OSAT



AI&IT/COMPUTING/  
AUTOMOTIVE/ELECTRONICS,  
ETC.





# ASPS 2024 SHOW REPORT

Unique visitors



**9,467**

Exhibitors



**168** exhibitors



**328** booths

**33.1%** (3,135)

Day 1

**37.9%** (3,585)

Day 2

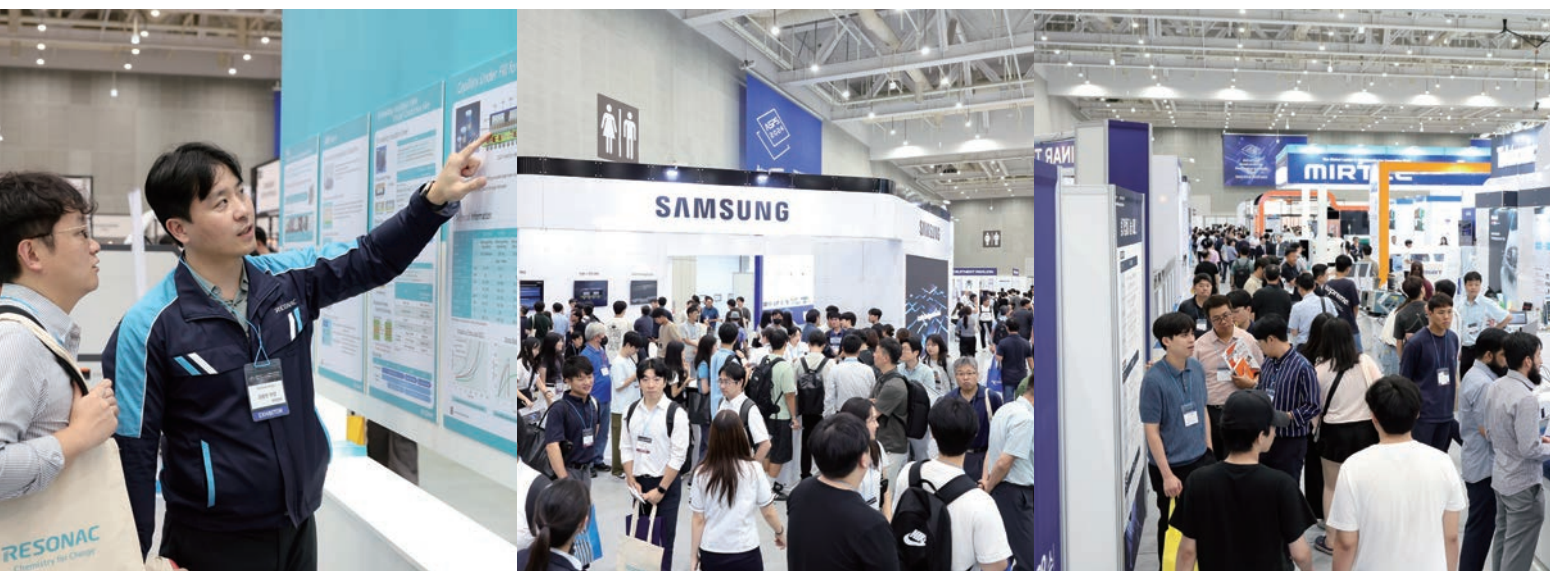
**29%** (2,747)

Day 3



## Key Visitors

- ALT
- AMKOR TECHNOLOGY
- APACT
- ASE KOREA
- ASML
- DB HITEK
- DENSO
- DONGWOO FINE-CHEM
- DOOSAN TESNA
- HANA MICRON
- HANWHA NXMD
- HYUNDAI MOBIS
- HYUNDAI MOTOR
- INTEL
- ITEK
- JCET STATS CHIPPAK KOREA
- LB LUSEM
- LB SEMICON
- LG ELECTRONICS
- LG INNOTEK
- MCNEX
- MEMSPACK
- NEPES
- NEPES ARK
- NEPES LAWEH
- PARTRON
- QUALCOMM
- SAMSUNG
- SAMSUNG ELECTRO-MECHANICS
- SAMSUNG SDI
- SAPIEN SEMICONDUCTORS
- SFA SEMICON
- SIEMENS
- SIGNETICS
- SK HYNIX
- SKAICHIPS
- STECO
- TEKLINE KOREA
- TEXAS INSTRUMENTS
- WINPAC





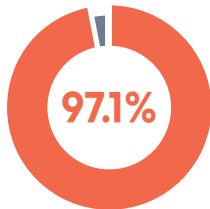
# EXHIBITOR FEEDBACK



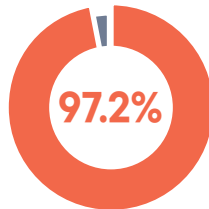
" I appreciated the opportunity to connect with clients we were collaborating with and exploring. "

" I was pleased with the many visits from professionals in semiconductor packaging. "

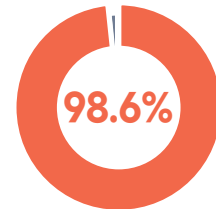
" I was able to gain a great promotional opportunity through participation in the exhibition, and it will likely be beneficial for future marketing as well. "



Organizer Operation Satisfaction



Visitor Satisfaction



Willing to Rebook



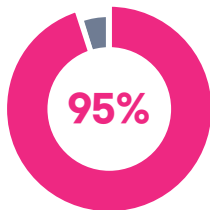
# VISITOR FEEDBACK



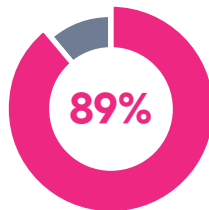
" The convenient location and the opportunity to gain insights into market trends made it a valuable experience. "

" It was an opportunity to learn about various companies in the semiconductor industry and share information. "

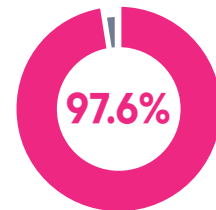
" The concurrent event was substantial and informative, allowing me to deepen my understanding of the semiconductor industry. "



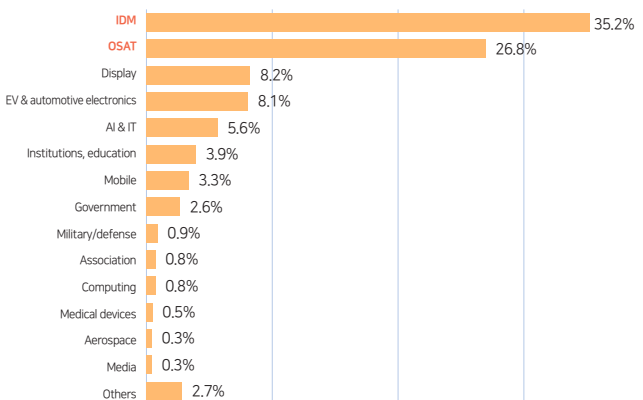
Overall Satisfaction



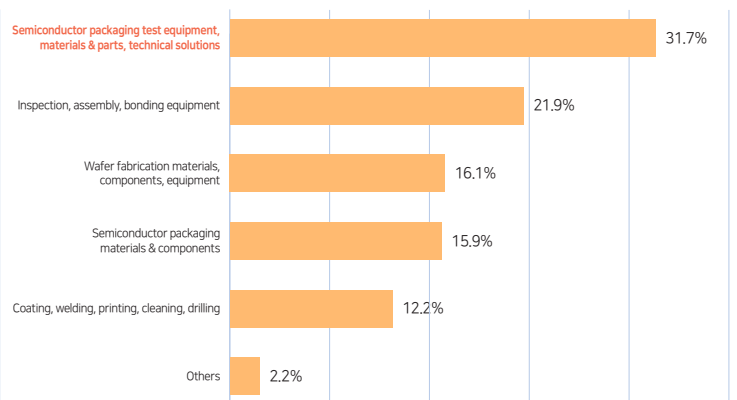
Exhibitor Satisfaction



Willing to Revisit



Classification by industry



Products of Interest





## BECOME AN EXHIBITOR



Request contract form



Sign & submit contract



Remit 1st payment (50% deposit)



Remit 2nd payment (50% remainder)



## PRICING

**Raw Space**



**USD 3,150 / booth**



- Space only booth
- Booth contractor required
- Starts from 2 booths



**Standard Booth**



**USD 3,600 / booth**



- A shell scheme booth
- Basic entitlements
- Starts from 1 booth



**Premium Booth**



**USD 4,500 / booth**



- A premium block booth
- Premium entitlements
- Starts from 2 booths

